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The SST12LP18E is a versatile power amplifier based on the highly-reliable InGaP/GaAs HBT technology. The SST12LP18E is a 2.4 GHz high-efficiency Power Amplifier designed in compliance with IEEE 802.11b/g/n/ac applications. It typically provides 25 dB gain with 32% power-added efficiency, while meeting 802.11g spectrum mask at 21.5 dBm. The SST12LP18E can be configured for high-linearity for 802.11ac operation or for high-power, high-efficiency operation. This power amplifier also features easy board-level usage along with high-speed power-up/down control through a single reference voltage pin and is offered in a 8-contact XSON package.

## Features

- **High gain:**
  - Typically 25 dB gain across 2.4~2.5 GHz
- **High linear output power:**
  - >26 dBm P1dB
  - Single-tone measurement
  - Please refer to “Absolute Maximum Stress Ratings” on page 5
  - Meets 802.11g OFDM ACPR requirement up to 21.5 dBm
  - Meets 802.11b ACPR requirement up to 22.5 dBm
  - ~3% added EVM up to 18 dBm for 54 Mbps 802.11g signal
  - 17 dBm at 1.8% EVM, 802.11ac, 256 QAM, 2.4 GHz
- **High power-added efficiency/Low operating current for 802.11b/g/n applications**
  - ~32%/135 mA @  $P_{OUT} = 21.5$  dBm for 802.11g
  - ~36%/150 mA @  $P_{OUT} = 22.5$  dBm for 802.11b
- **Single-pin low  $I_{REF}$  power-up/down control**
  - $I_{REF} < 2$  mA
- **Low idle current for high-efficiency operation**
  - ~50 mA  $I_{CQ}$
- **High-speed power-up/down control**
  - Turn on/off time (10%- 90%) <100 ns
  - Typical power-up/down delay with driver delay included <200 ns
- **Low shut-down current (~2  $\mu$ A)**
- **Limited variation over temperature**
  - ~1 dB gain/power variation between -20°C to +85°C
- **Excellent on-chip power detection**
  - >15 dB dynamic range on-chip power detection
  - Temperature and VSWR insensitive
- **Simple output matching**
- **Packages available**
  - 8-contact XSON – 2mm x 2mm
- **All non-Pb (lead-free) devices are RoHS compliant**

## Applications

- WLAN (IEEE 802.11b/g/n/ac)
- Home RF
- Cordless phones
- 2.4 GHz ISM wireless equipment



### Product Description

The SST12LP18E is a versatile power amplifier based on the highly-reliable InGaP/GaAs HBT technology.

The SST12LP18E is a 2.4 GHz high-efficiency Power Amplifier designed in compliance with IEEE 802.11b/g/n/ac applications. It typically provides 25 dB gain with 32% power-added efficiency (PAE) @ POUT = 21.5 dBm for 802.11g and 36% PAE @ POUT = 22.5 dBm for 802.11b.

The SST12LP18E has excellent linearity, typically ~3% added EVM at 18 dBm output power which is essential for 54 Mbps 802.11g operation while meeting 802.11g spectrum mask at 21.5 dBm. SST12LP18E can also be configured for high-linearity with EVM <1.8% at typically 17 dBm for 802.11ac operation.

The SST12LP18E also features easy board-level usage along with high-speed power-up/down control through a single combined reference voltage pin. Ultra-low reference current (total I<sub>REF</sub> ~2 mA) makes the SST12LP18E controllable by an on/off switching signal directly from the baseband chip. These features, coupled with low operating current, make the SST12LP18E ideal for the final stage power amplification in battery-powered 802.11b/g/n/ac WLAN transmitter applications.

The SST12LP18E has an excellent on-chip, single-ended power detector, which features wide-range (>15 dB) with dB-wise linear operation. The excellent on-chip power detector is both temperature and VSWR insensitive; therefore, it provides a reliable solution to board-level power control.

The SST12LP18E is offered in 8-contact XSON package. See Figure 2 for pin assignments and Table 1 for pin descriptions.



### Functional Blocks

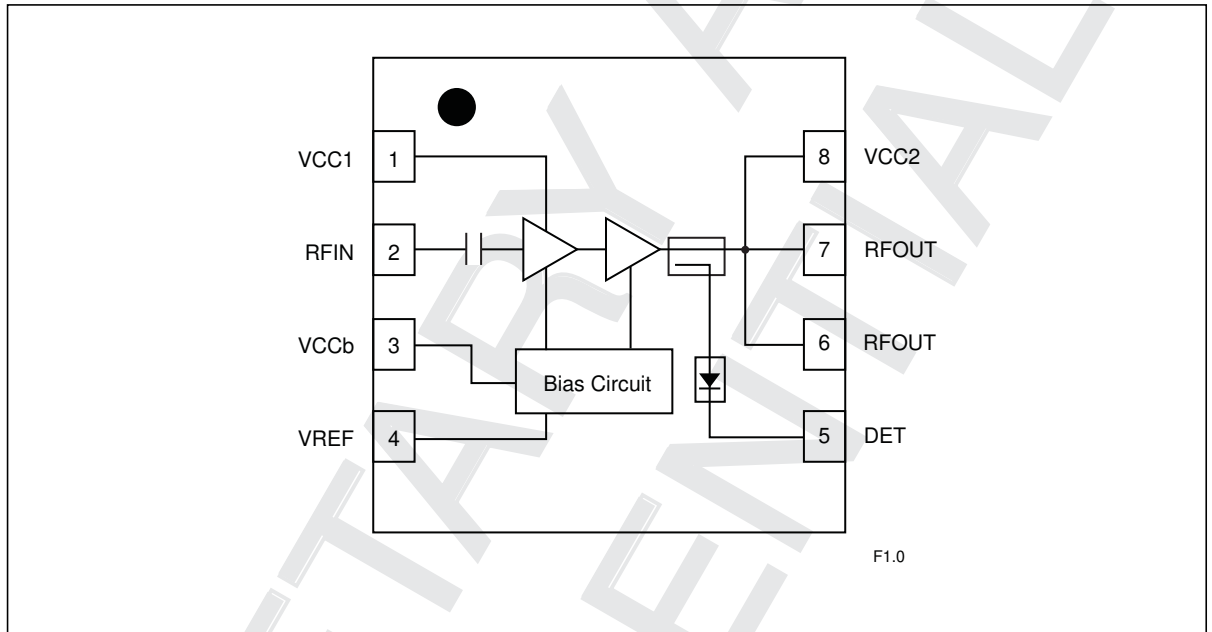


Figure 1: Functional Block Diagram



### Pin Assignments

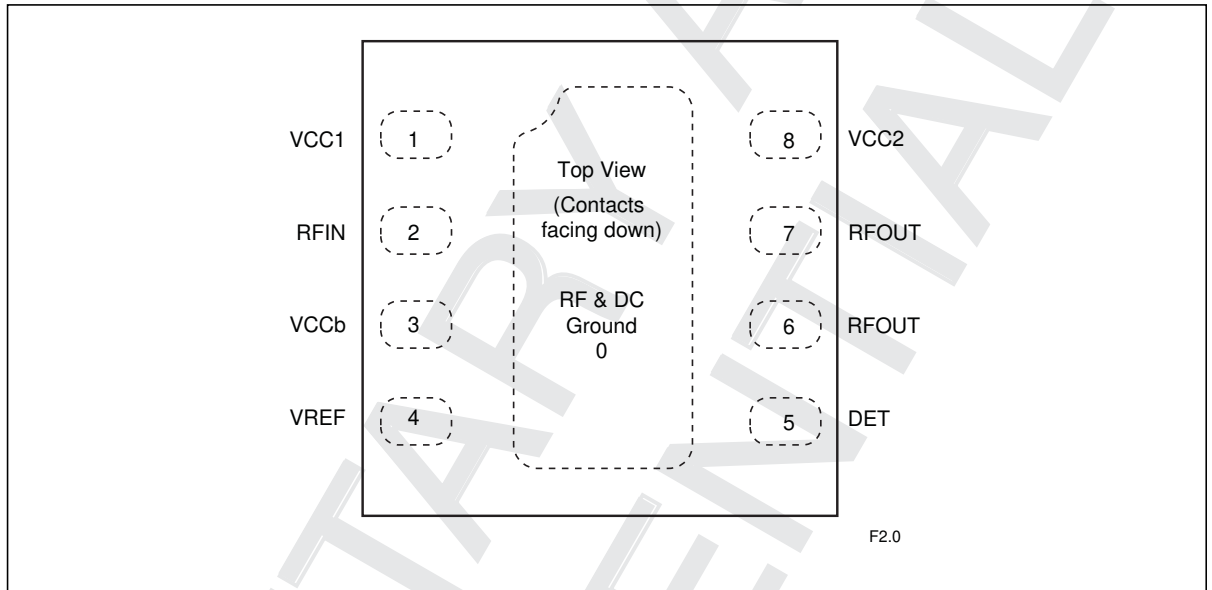


Figure 2: Pin Assignments for 8-contact XSON

### Pin Descriptions

Table 1: Pin Description

| Symbol            | Pin No. | Pin Name     | Type <sup>1</sup> | Function   |
|-------------------|---------|--------------|-------------------|--|
| GND               | 0       | Ground       |                   | Low inductance GND pad   |
| V <sub>CC1</sub>  | 1       | Power Supply | PWR               | Power supply, 1 <sup>st</sup> stage                            |
| R <sub>FIN</sub>  | 2       |              | I                 | RF input, DC decoupled   |
| V <sub>CCb</sub>  | 3       | Power Supply | PWR               | Supply voltage for bias circuit                                |
| V <sub>REF</sub>  | 4       |              | PWR               | 1 <sup>st</sup> and 2 <sup>nd</sup> stage idle current control |
| Det               | 5       |              | O                 | On-chip power detector   |
| R <sub>FOUT</sub> | 6       |              | O                 | RF output  |
| R <sub>FOUT</sub> | 7       |              | O                 | RF output  |
| V <sub>CC2</sub>  | 8       | Power Supply | PWR               | Power supply, 2 <sup>nd</sup> stage                            |

1. I=Input, O=Output



# 2.4 GHz High-Efficiency, High-Gain Power Amplifier

## SST12LP18E

Data Sheet

### Electrical Specifications

The DC and RF specifications for the power amplifier are specified below. Refer to Table 3 for the DC voltage and current specifications. Refer to Figures 3 through 13 for the RF performance.

**Absolute Maximum Stress Ratings** (Applied conditions greater than those listed under “Absolute Maximum Stress Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these conditions or conditions greater than those defined in the operational sections of this data sheet is not implied. Exposure to absolute maximum stress rating conditions may affect device reliability.)

|   |                      |
|---|----------------------|
| Input power to pin 2 ( $P_{IN}$ )               | +5 dBm               |
| Average output power ( $P_{OUT}$ ) <sup>1</sup> | +26 dBm              |
| Supply Voltage at pins 1, 3, and 8 ( $V_{CC}$ ) | -0.3V to +4.2V       |
| Reference voltage to pin 4 ( $V_{REF}$ )        | -0.3V to +3.3V       |
| DC supply current ( $I_{CC}$ ) <sup>2</sup>     | 300 mA               |
| Operating Temperature ( $T_A$ )                 | -40°C to +85°C       |
| Storage Temperature ( $T_{STG}$ )               | -40°C to +120°C      |
| Maximum Junction Temperature ( $T_J$ )          | +150°C               |
| Surface Mount Solder Reflow Temperature         | 260°C for 10 seconds |

- Never measure with CW source. Pulsed single-tone source with <50% duty cycle is recommended. Exceeding the maximum rating of average output power could cause permanent damage to the device.
- Measured with 100% duty cycle 54 Mbps 802.11g OFDM Signal

**Table 2: Operating Range**

| Range      | Ambient Temp   | $V_{CC}$ |
|------------|----------------|----------|
| Industrial | -40°C to +85°C | 3.3V     |

T2.1 75003

**Table 3: DC Electrical Characteristics at 25°C for High-Linearity Configurations<sup>1</sup>**

| Symbol    | Parameter   | Min. | Typ | Max. | Unit |
|-----------|---|------|-----|------|------|
| $V_{CC}$  | Supply Voltage at pins 1,3,and 8  | 3.0  | 3.3 | 3.6  | V    |
| $I_{CQ}$  | Idle current to meet EVM ~1.8% @ 17 dBm Output Power with 802.11g OFDM 54 Mbps signal |      | 110 |      | mA   |
| $I_{CC}$  | Current Consumption @ 18 dBm Output Power with 802.11g OFDM 54 Mbps signal            |      | 140 |      |      |
|           | Current Consumption to meet 802.11g OFDM 6 Mbps Spectrum mask @ 21.5 dBm Output Power |      | 170 |      | mA   |
|           | Current Consumption to meet 802.11b DSSS 1 Mbps Spectrum mask @ 22.5 dBm Output Power |      | 180 |      | mA   |
| $V_{REG}$ | Reference Voltage with 0Ω resistor  | 2.7  | 2.8 | 2.9  | V    |

T3.1 75003

- See Figure 8



# 2.4 GHz High-Efficiency, High-Gain Power Amplifier SST12LP18E

**Table 4:** DC Electrical Characteristics at 25°C for High-Efficiency Configurations<sup>1</sup>

| Symbol           | Parameter   | Min. | Typ | Max. | Unit |
|------------------|---|------|-----|------|------|
| V <sub>CC</sub>  | Supply Voltage at pins 1,3,and 8  | 3.0  | 3.3 | 3.6  | V    |
| I <sub>CQ</sub>  | Idle current to meet EVM ~3% @ 18 dBm Output Power with 802.11g OFDM 54 Mbps signal   |      | 50  |      | mA   |
| I <sub>CC</sub>  | Current Consumption @ 18 dBm Output Power with 802.11g OFDM 54 Mbps signal            |      | 95  |      |      |
|                  | Current Consumption to meet 802.11g OFDM 6 Mbps Spectrum mask @ 21.5 dBm Output Power |      | 135 |      | mA   |
|                  | Current Consumption to meet 802.11b DSSS 1 Mbps Spectrum mask @ 22.5 dBm Output Power |      | 150 |      | mA   |
| V <sub>REG</sub> | Reference Voltage with 360Ω resistor  | 2.7  | 2.8 | 2.9  | V    |

T4.1 75003

1. See Figure 14

**Table 5:** RF Electrical Characteristics at 25°C

| Symbol            | Parameter  | Min. | Typ  | Max. | Unit |
|-------------------|--|------|------|------|------|
| F <sub>L-U</sub>  | Frequency range  | 2412 |      | 2484 | MHz  |
| G                 | Small signal gain  | 24   | 25   |      | dB   |
| G <sub>VAR1</sub> | Gain variation over band (2412–2484 MHz)                               |      |      | ±0.5 | dB   |
| G <sub>VAR2</sub> | Gain ripple over channel (20 MHz)                                      |      | 0.2  |      | dB   |
| EVM               | EVM@ 18 dBm Output Power with 802.11g OFDM 54 Mbps signal <sup>1</sup> |      | 3.0  |      | %    |
|                   | EVM@ 17 dBm Output Power with 802.11ac 20 MHz BW <sup>2</sup>          |      | 1.8  |      | %    |
| P <sub>OUT</sub>  | Output Power to meet 802.11g OFDM 6 Mbps Spectrum mask                 | 20.5 | 21.5 |      | dBm  |
|                   | Output Power to meet 802.11b DSSS 1 Mbps Spectrum mask                 | 21.5 | 22.5 |      | dBm  |
| 2f, 3f, 4f, 5f    | Harmonics at 23 dBm, without external filters                          |      |      | -30  | dBc  |

T5.2 75003

1. See Figure 14

2. See Figure 8

**Table 6:** Typical Performance with Different Bias Options for High-Efficiency Configuration

| V <sub>REG</sub> (V) | R <sub>1</sub> <sup>1</sup> (Ω) | I <sub>CQ</sub> <sup>2</sup> (mA) | I <sub>CC</sub> @ P <sub>OUT</sub> =18 dBm <sup>2</sup> (mA) | Typical Performance with Each Biased Option            |
|----------------------|---------------------------------|-----------------------------------|--|--|
| 2.85                 | 500                             | 45                                | 95   | Meet added EVM < 3% up to 18 dBm output power at -40°C |
| 2.80                 | 360                             | 50                                | 95   | Meet added EVM < 3% up to 18 dBm output power at -40°C |
| 2.70                 | 180                             | 50                                | 95   | Meet added EVM < 3% up to 18 dBm output power at -20°C |
| 2.70                 | 33                              | 72                                | 110  | Meet added EVM < 3% up to 18 dBm output power at -40°C |
| 2.70                 | 0                               | 82                                | 120  | Meet added EVM < 3% up to 18 dBm output power at -40°C |

T6.1 75003

1. See Figure 14

2. At room temperature



# 2.4 GHz High-Efficiency, High-Gain Power Amplifier SST12LP18E

## Typical Performance Characteristics

Test Conditions:  $V_{CC} = 3.3V$ ,  $T_A = 25^\circ C$ , unless otherwise specified

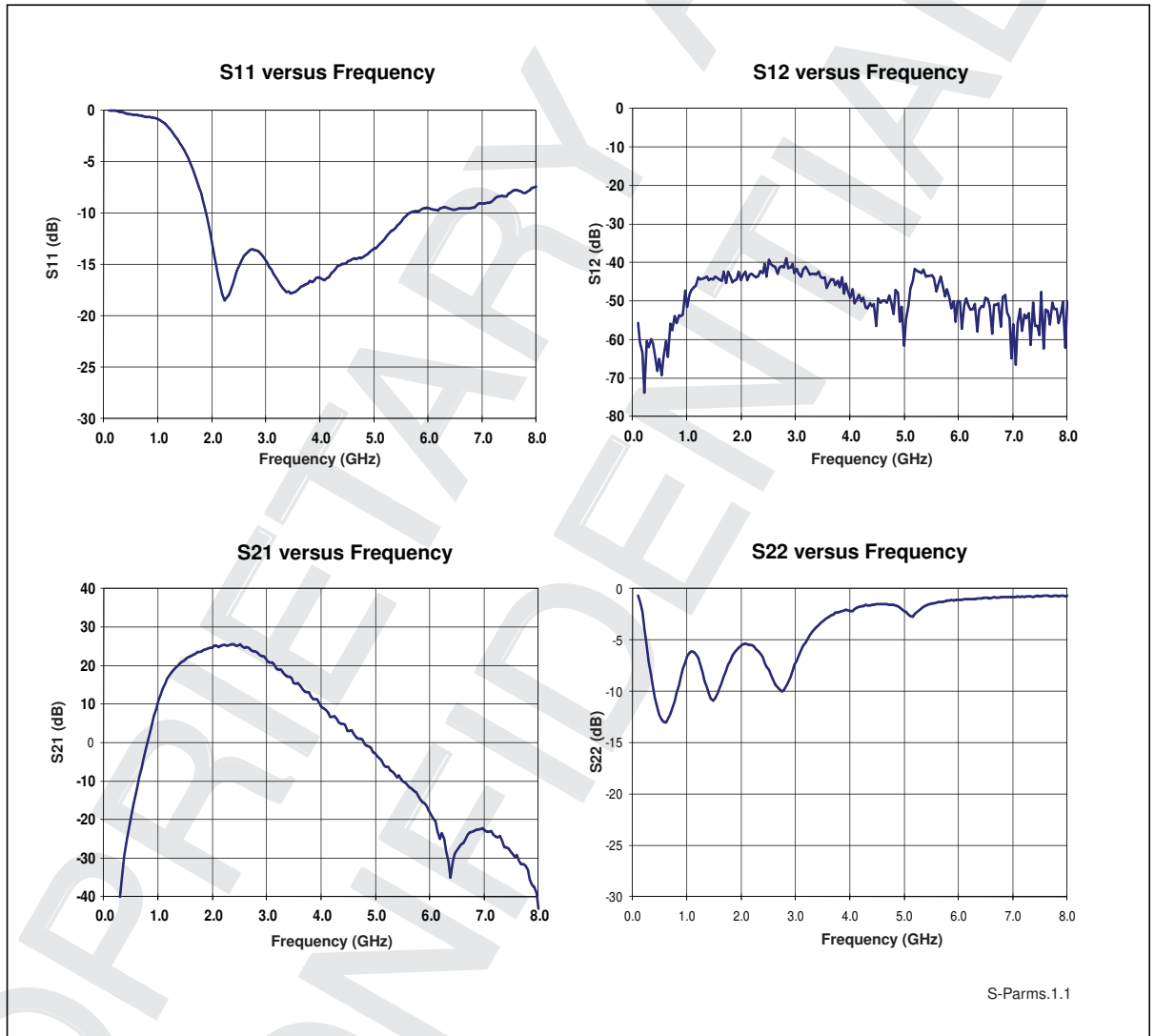


Figure 3: S-Parameters





### High-Linearity Configuration for 802.11b/g/n/ac

#### Typical Performance Characteristics

Test Conditions:  $V_{CC} = 3.3V$ ,  $V_{REF} = 2.8V$ ,  $T_A = 25^\circ C$ , 54 Mbps 802.11g OFDM Signal; Equalizer Training Setting using Channel Estimation Sequence Only

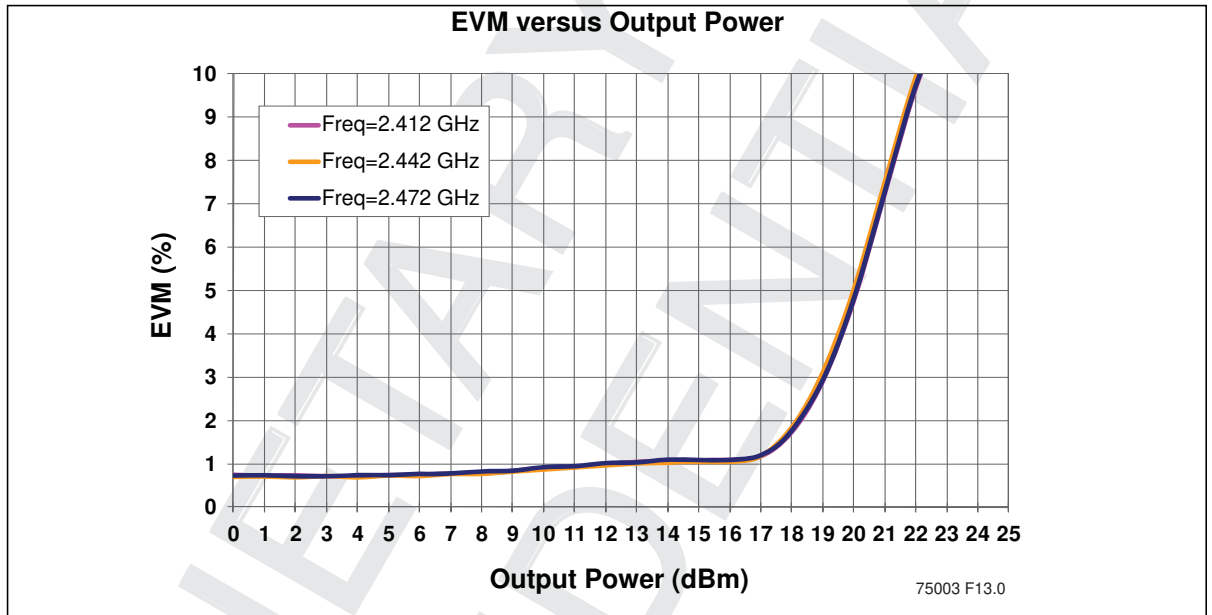


Figure 4: EVM versus Output Power

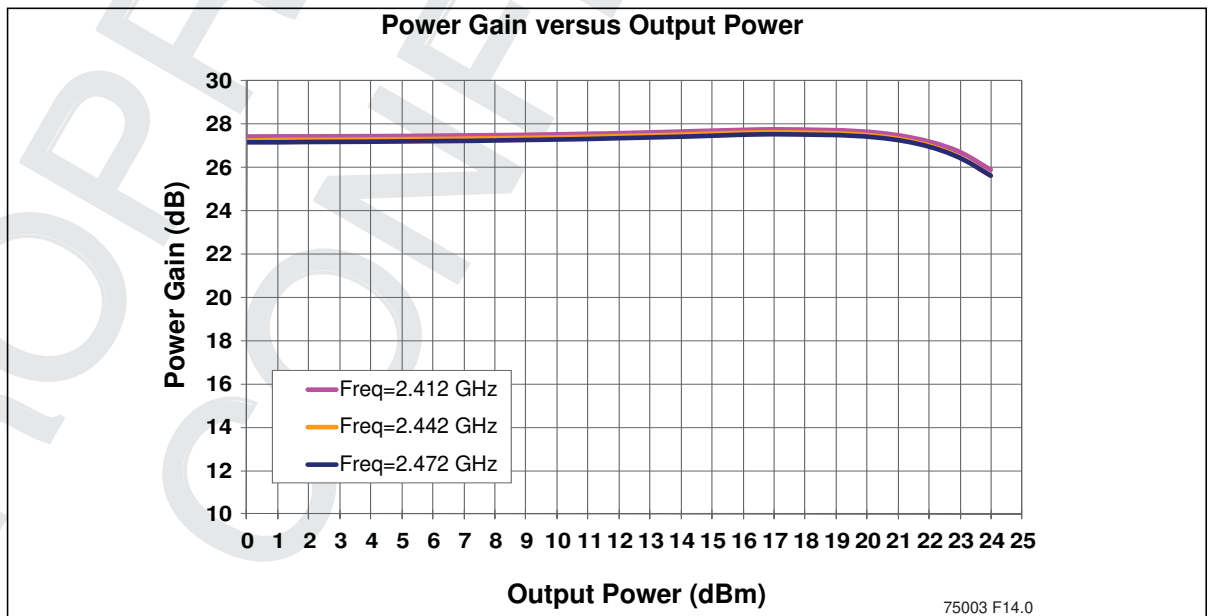


Figure 5: Power Gain versus Output Power



### High-Linearity Configuration (continued)

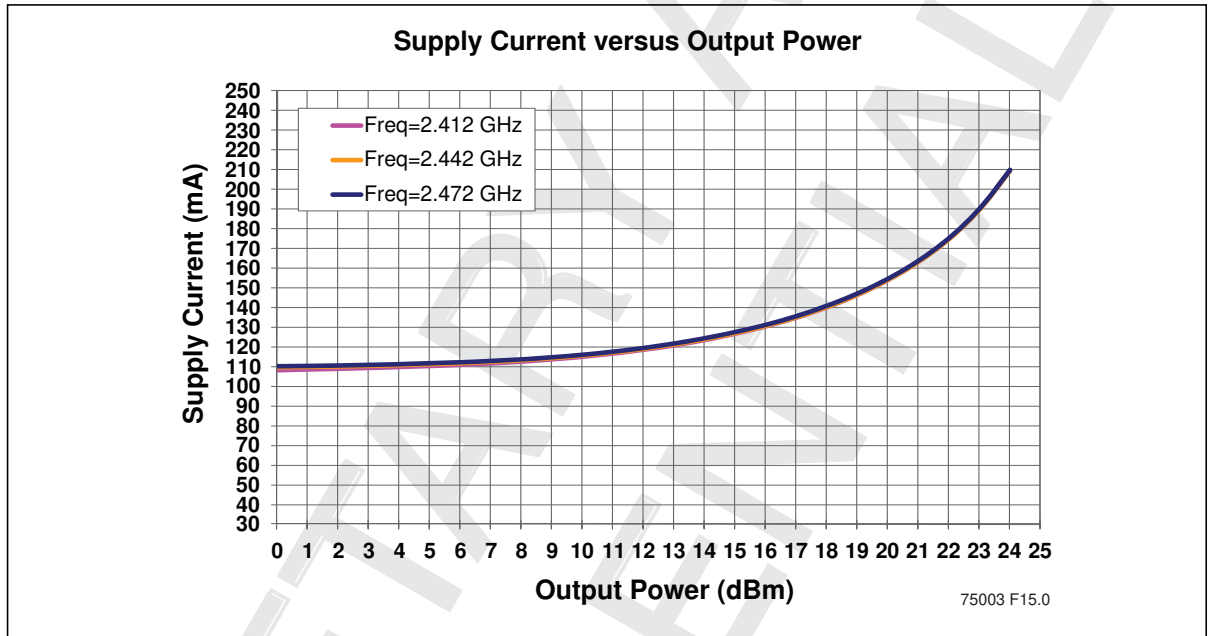


Figure 6: Total Current Consumption for 802.11g operation versus Output Power

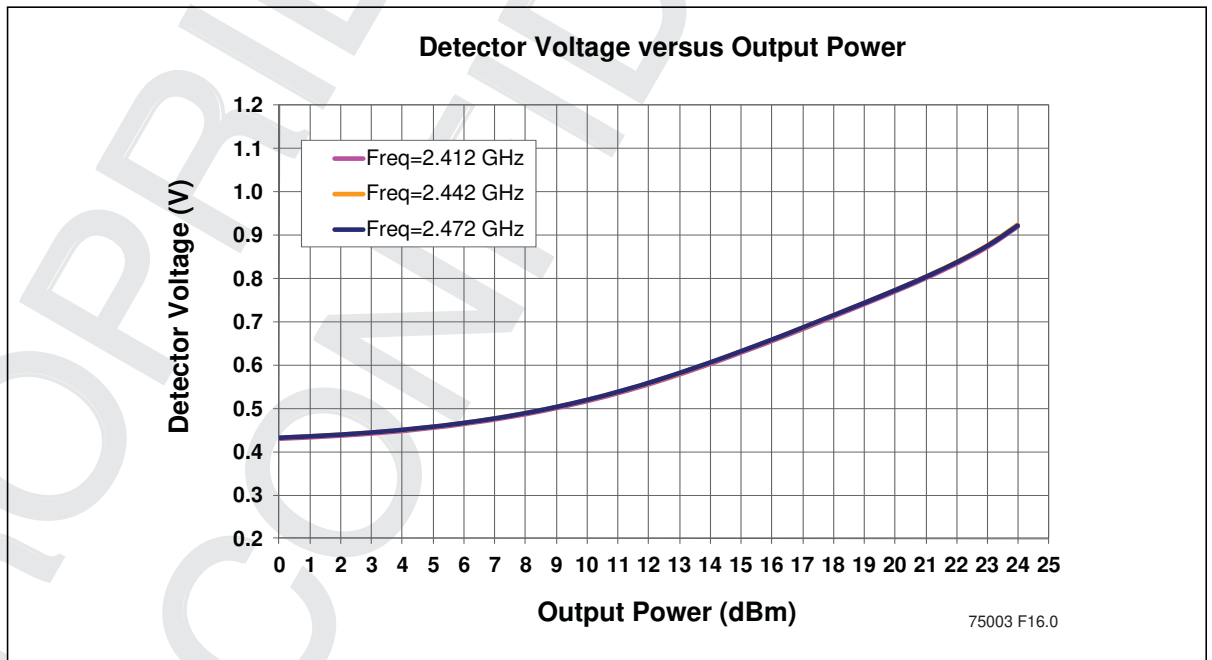


Figure 7: Detector Characteristics versus Output Power



### High-Linearity Configuration (continued)

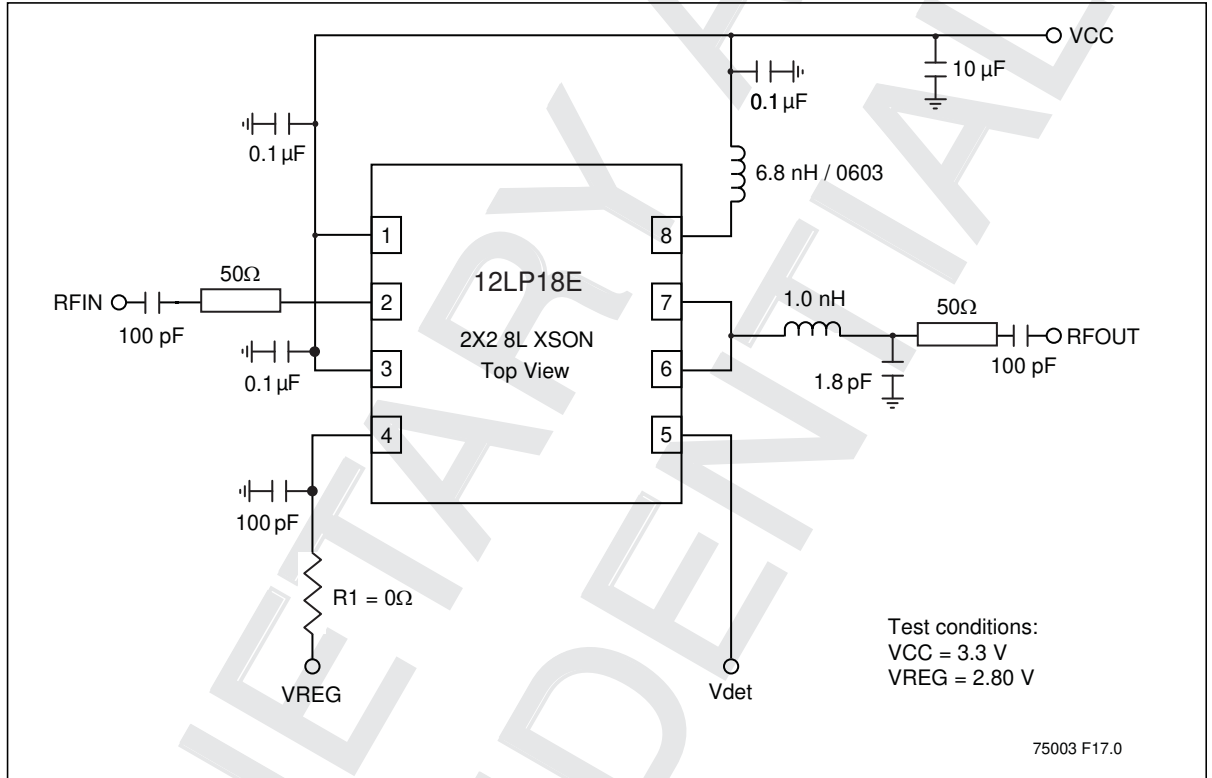


Figure 8: Typical Schematic for High-Linearity 802.11b/g/n/ac Applications



### High-Efficiency Configuration for 802.11b/g/n Operation

#### Typical Performance Characteristics

Test Conditions:  $V_{CC} = 3.3V$ ,  $V_{REF} = 2.8V$ ,  $T_A = 25^\circ C$ , 54 Mbps 802.11g OFDM Signal; Equalizer Training Setting using Channel Estimation Sequence Only

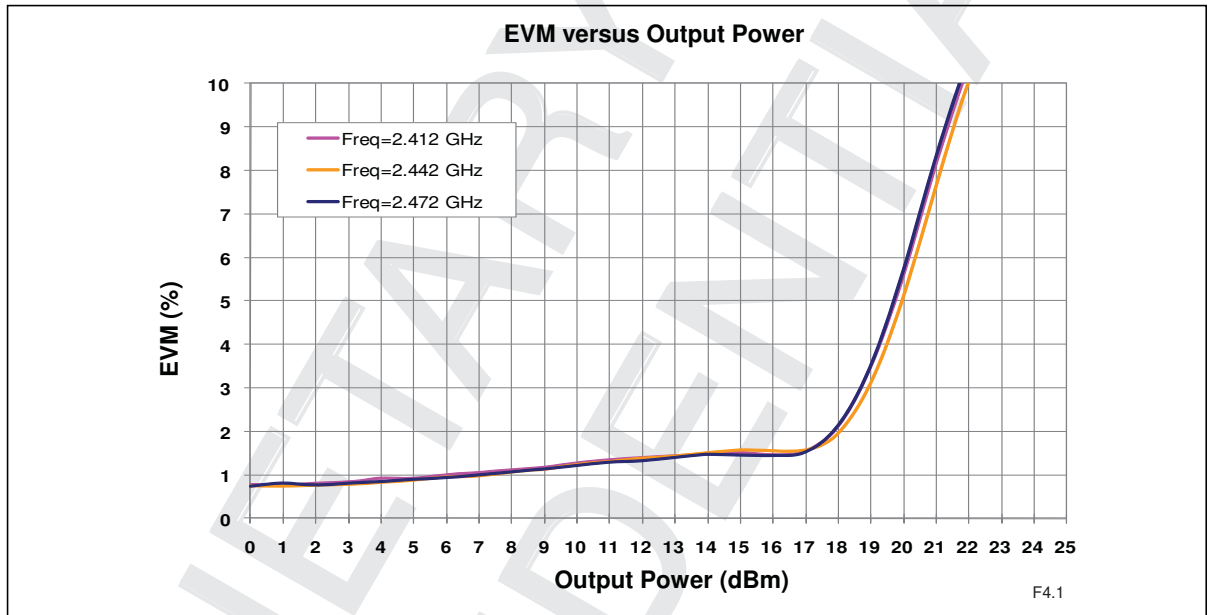


Figure 9: EVM versus Output Power

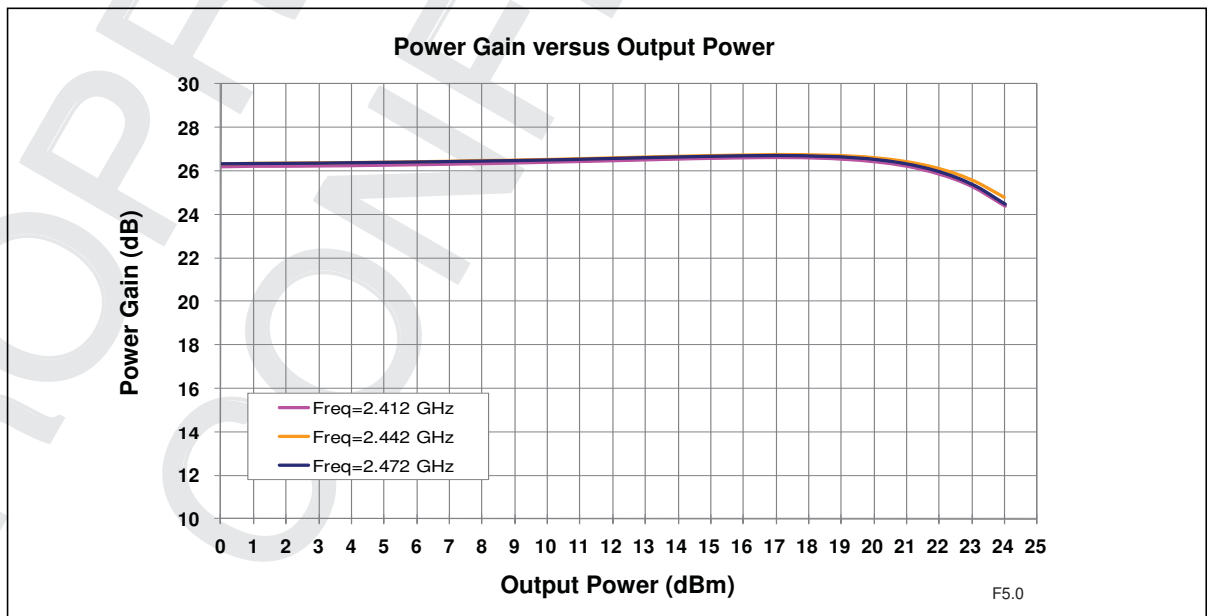


Figure 10: Power Gain versus Output Power



### High-Efficiency Configuration (continued)

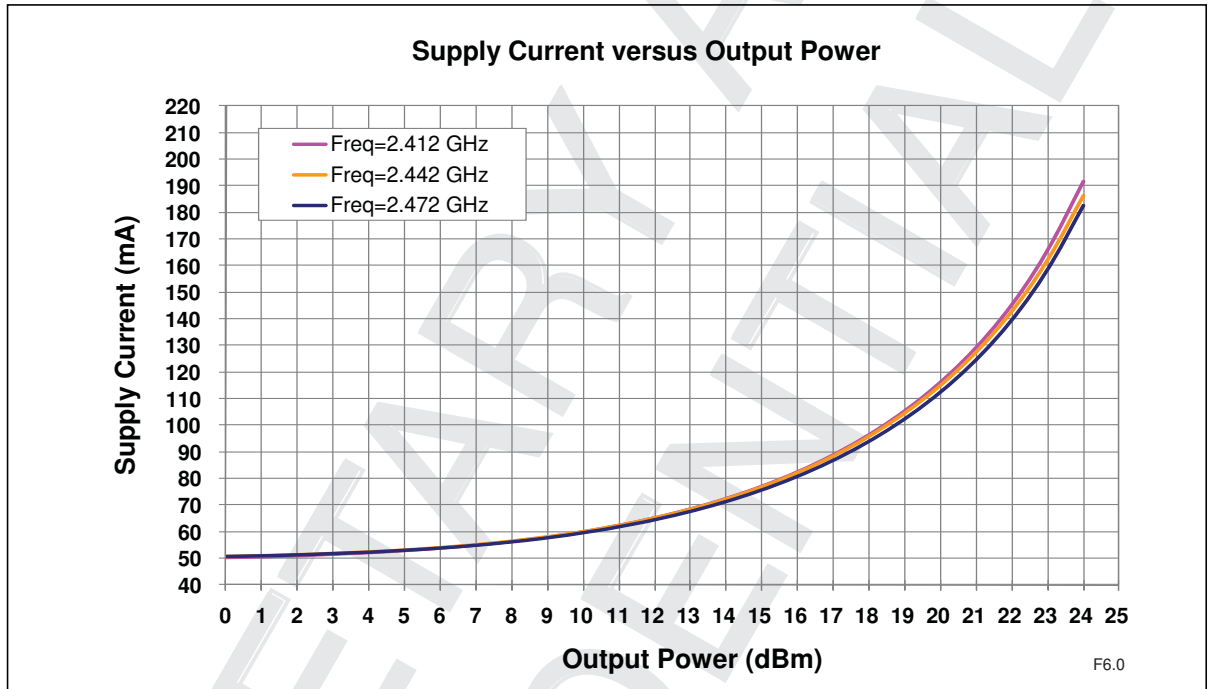


Figure 11: Total Current Consumption for 802.11g operation versus Output Power

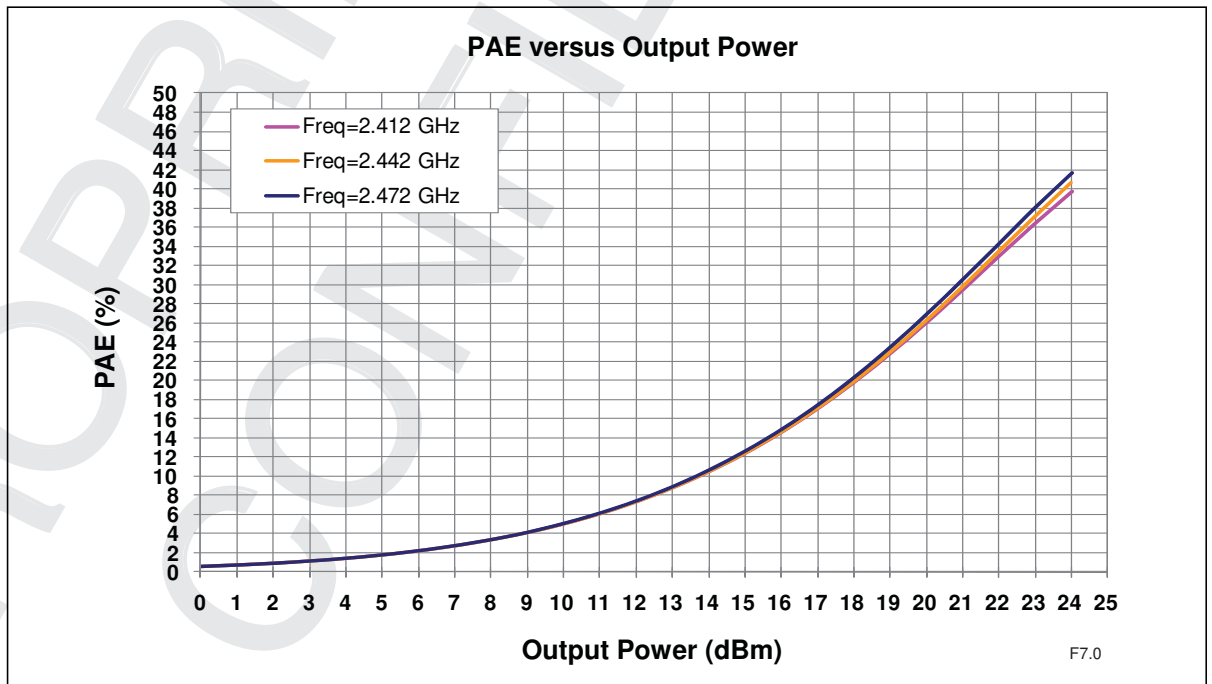


Figure 12: PAE versus Output Power



### High-Efficiency Configuration (continued)

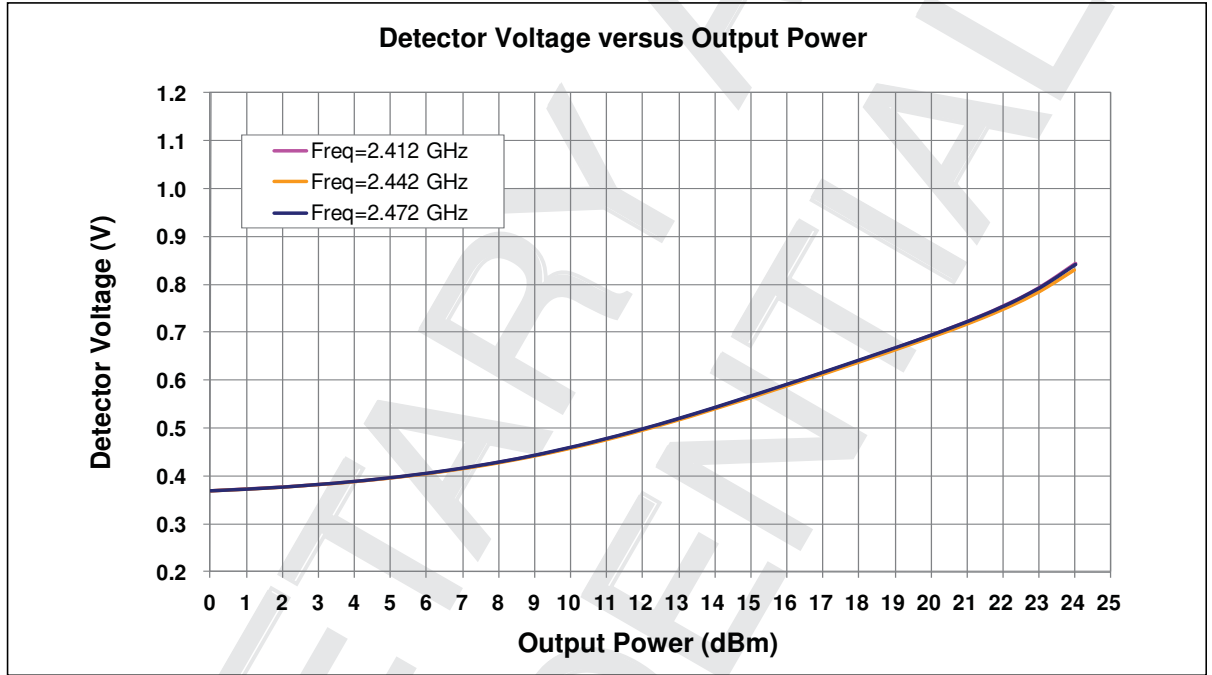


Figure 13: Detector Characteristics versus Output Power



### High-Efficiency Configuration (continued)

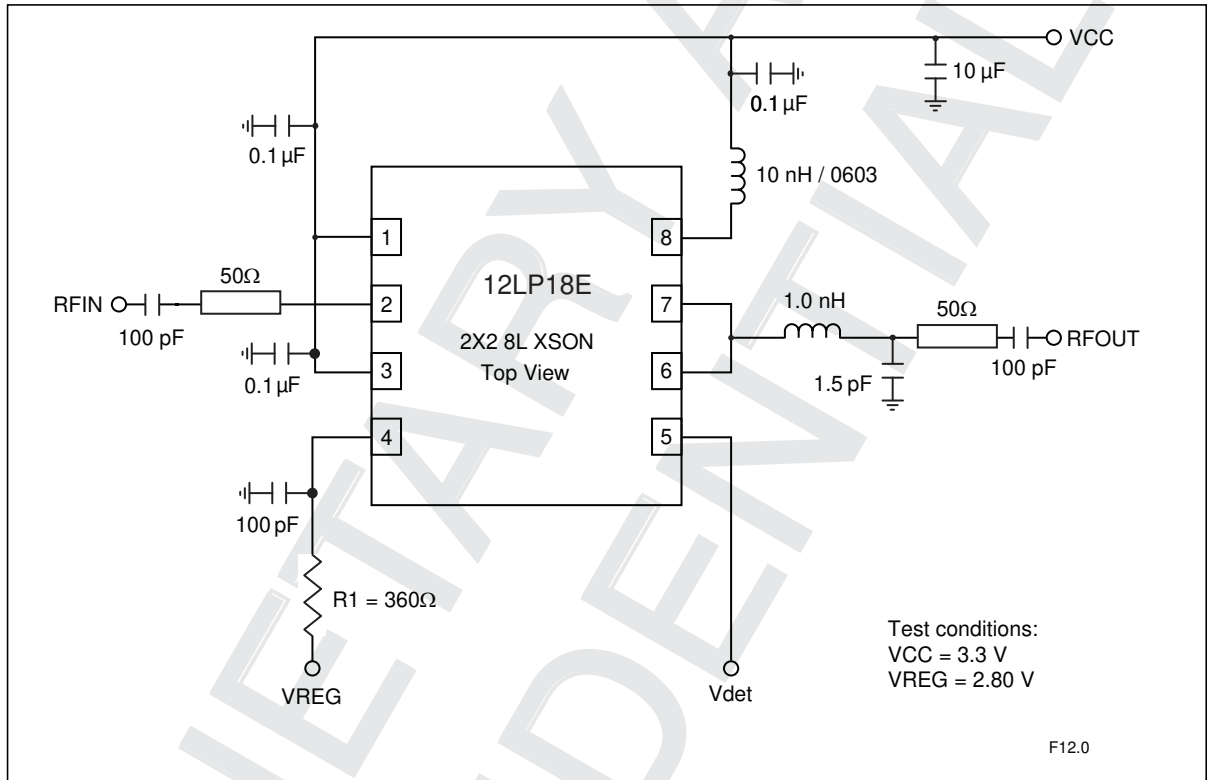
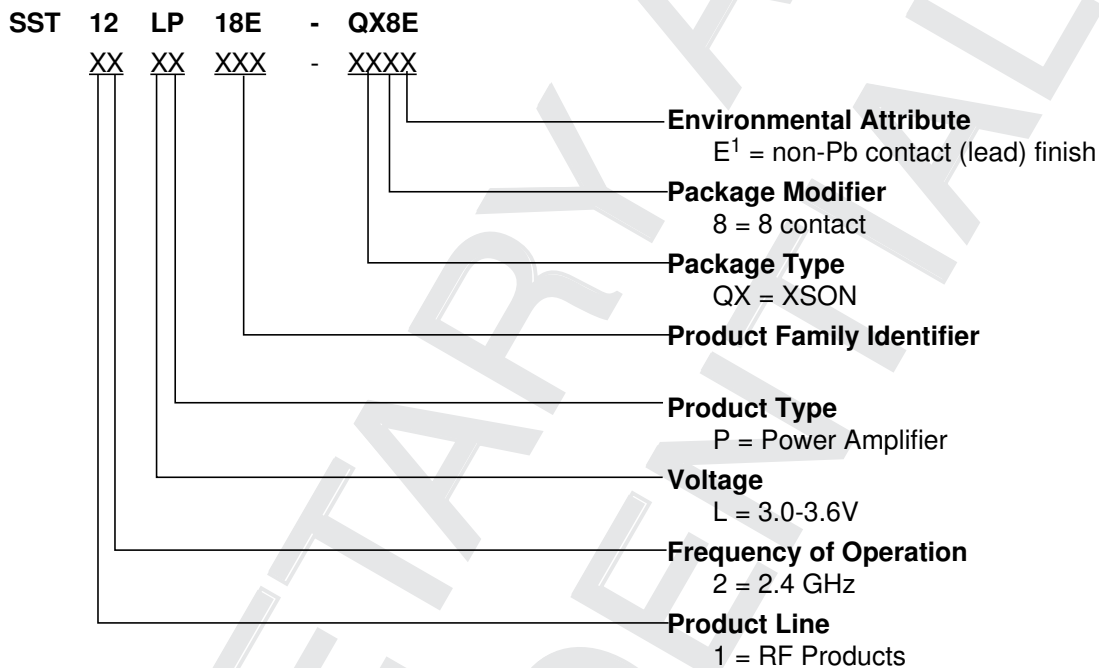


Figure 14: Typical Schematic for High-Efficiency 802.11b/g/n Applications



### Product Ordering Information



1. Environmental suffix "E" denotes non-Pb solder. SST non-Pb solder devices are "RoHS Compliant".

#### Valid combinations for SST12LP18E

SST12LP18E-QX8E

#### SST12LP18E Evaluation Kits

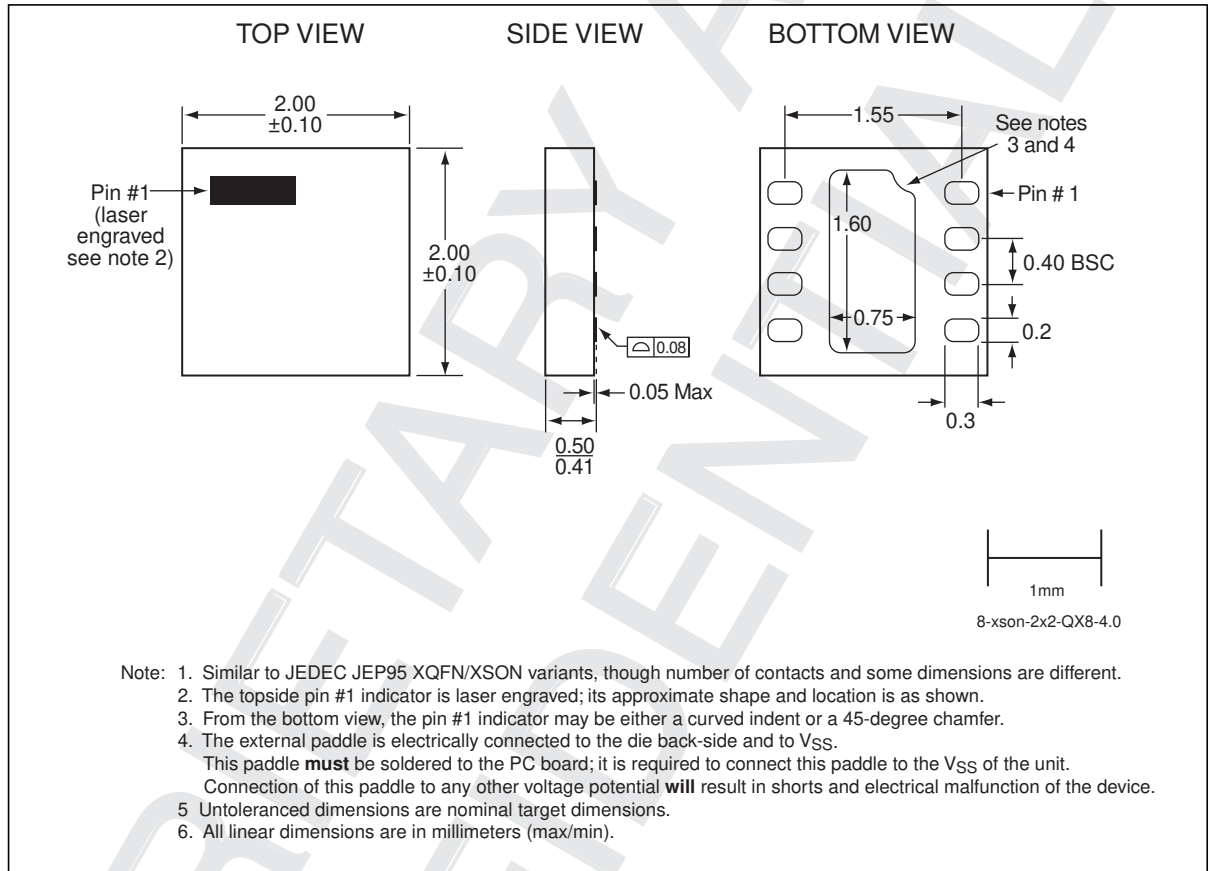
SST12LP18E-QX8E-K

**Note:** Valid combinations are those products in mass production or will be in mass production. Consult your SST sales representative to confirm availability of valid combinations and to determine availability of new combinations.





### Packaging Diagrams



**Figure 15:8-Contact Extremely-thin Small Outline No-lead (XSON)**  
SST Package Code: QX8



# 2.4 GHz High-Efficiency, High-Gain Power Amplifier SST12LP18E

**Table 7:**Revision History

| Revision | Description  | Date     |
|----------|--|----------|
| A        | <ul style="list-style-type: none"> <li>Initial release of data sheet</li> </ul>  | Mar 2011 |
| B        | <ul style="list-style-type: none"> <li>Revised “Electrical Specifications” on page 5 from 4.0V max stress to 4.6V</li> <li>Updated Figure 9 on page 11 to show “sequence only” EVM response</li> </ul>   | Mar 2012 |
| C        | <ul style="list-style-type: none"> <li>Added Figures 9-8 on pages 11-10 to provide High-Linearity information</li> <li>Updated Table 5 on page 6</li> <li>Updated Figure 15 on page 16 to reflect new pin 1 indicator</li> <li>Clarified Features on page 1</li> </ul> | Jul 2012 |

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